

L Number	Hits	Search Text	DB	Time stamp
2	165	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and etch\$3) and (trench recess open\$3 hole groove)) and (semiconductor wafer substrate)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel)))) and (PR photoresist resist photo?resist)) and resin) and ((electoless near3 plat\$3) electo?plat\$3 (electro near3 plat\$3))	USPAT; US-PGPUB	2004/03/31 12:04
3	0	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and etch\$3) and (trench recess open\$3 hole groove)) and (semiconductor wafer substrate)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel)))) and (PR photoresist resist photo?resist)) and resin) and ((electoless near3 plat\$3) electo?plat\$3 (electro near3 plat\$3))	EPO; JPO; DERWENT; IBM_TDB	2004/03/31 12:04
4	12105	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and (trench recess open\$3 hole groove)) and resin	USPAT; US-PGPUB	2004/03/31 12:05
5	288	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and (trench recess open\$3 hole groove)) and resin	EPO; JPO; DERWENT; IBM_TDB	2004/03/31 12:05
6	38	(conductive near3 foil) and (isolat\$3 near5 trench)	USPAT; US-PGPUB	2004/03/31 12:06
7	34	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and (trench recess open\$3 hole groove)) and resin) and (conductive near3 foil) and (isolat\$3 near5 trench)	USPAT; US-PGPUB	2004/03/31 12:08
8	38	((conductive near3 foil) and (isolat\$3 near5 trench)) ((((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and (trench recess open\$3 hole groove)) and resin) and (conductive near3 foil) and (isolat\$3 near5 trench))	USPAT; US-PGPUB	2004/03/31 12:06
9	0	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and (trench recess open\$3 hole groove)) and resin) and (conductive near3 foil) and (isolat\$3 near5 trench)	EPO; JPO; DERWENT; IBM_TDB	2004/03/31 12:08